

February 2008

74LVX74 Low Voltage Dual D-Type Positive Edge-Triggered Flip-Flop

Features

- Input voltage level translation from 5V to 3V
- Ideal for low power/low noise 3.3V applications
- Guaranteed simultaneous switching noise level and dynamic threshold performance

General Description

The LVX74 is a dual D-type flip-flop with Asynchronous Clear and Set inputs and complementary $(Q,\,\overline{Q})$ outputs. Information at the input is transferred to the outputs on the positive edge of the clock pulse. After the Clock Pulse input threshold voltage has been passed, the Data input is locked out and information present will not be transferred to the outputs until the next rising edge of the Clock Pulse input.

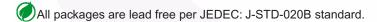
Asynchronous Inputs:

- LOW input to SD (Set) sets Q to HIGH level
- LOW input to \overline{C}_D (Clear) sets Q to LOW level
- Clear and Set are independent of clock
- Simultaneous LOW on \overline{C}_D and \overline{S}_D makes both Q and \overline{Q} HIGH

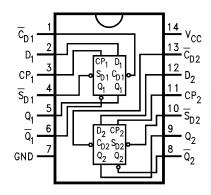
Ordering Information

Order Number	Package Number	Package Description
74LVX74M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LVX74SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVX74MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



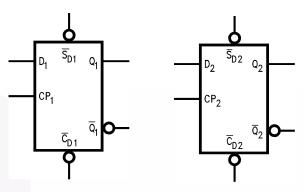
Connection Diagram



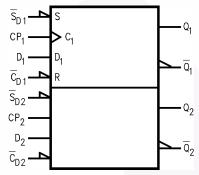
Pin Description

Pin Names	Description
D ₁ , D ₂	Data Inputs
CP ₁ , CP ₂	Clock Pulse Inputs
$\overline{C}_{D1}, \overline{C}_{D2}$	Direct Clear Inputs
$\overline{S}_{D1}, \overline{S}_{D2}$	Direct Set Inputs
$Q_1, \overline{Q}_1, Q_2, \overline{Q}_2$	Outputs

Logic Symbols



IEEE/IEC



Truth Table

(Each Half)

	Inp	Out	puts		
\overline{S}_{D}	<u>C</u> D	СР	D	Q	Q
L	Н	Х	X	Н	L
Н	L	Х	Х	L	Н
L	L	Х	Х	Н	Н
Н	Н	_	Н	Н	L
Н	Н		L	L	Н
Н	Н	L	Х	Q_0	\overline{Q}_0

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

∠ = LOW-to-HIGH Clock Transition

 $\mathsf{Q}_0(\overline{\mathsf{Q}}_0) = \mathsf{Previous}\; \mathsf{Q}(\overline{\mathsf{Q}})$ before LOW-to-HIGH Transition of Clock

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
I _{IK}	DC Input Diode Current, V _I = -0.5V	–20mA
V _I	DC Input Voltage	-0.5V to 7V
I _{OK}	DC Output Diode Current	
	$V_{O} = -0.5V$	–20mA
	$V_O = V_{CC} + 0.5V$	+20mA
V _O	DC Output Voltage	-0.5V to V _{CC} + 0.5V
I _O	DC Output Source or Sink Current	±25mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current	±50mA
T _{STG}	Storage Temperature	−65°C to +150°C
Р	Power Dissipation	180mW

Recommended Operating Conditions⁽¹⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	2.0V to 3.6V
V _I	Input Voltage	0V to 5.5V
Vo	Output Voltage	0V to V _{CC}
T _A	Operating Temperature	–40°C to +85°C
Δt / ΔV	Input Rise and Fall Time	0ns/V to 100ns/V

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

				TA	\ = +2 5	°C		40°C to 5°C	
Symbol	Parameter	V _{CC}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units
V _{IH}	HIGH Level Input	2.0		1.5			1.5		V
	Voltage	3.0		2.0			2.0		
		3.6		2.4			2.4		
V _{IL}	LOW Level Input	2.0				0.5		0.5	V
	Voltage	3.0				8.0		0.8	
		3.6				8.0		0.8	
V _{OH}	HIGH Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50\mu\text{A}$	1.9	2.0		1.9		V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50\mu\text{A}$	2.9	3.0		2.9		
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -4\text{mA}$	2.58			2.48		
V _{OL}	LOW Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 50\mu\text{A}$		0.0	0.1		0.1	V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 50 \mu A$		0.0	0.1		0.1	
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 4\text{mA}$			0.36		0.44	
I _{IN}	Input Leakage Current	3.6	V _{IN} = 5.5V or GND			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	3.6	$V_{IN} = V_{CC}$ or GND			2.0		20.0	μA

Noise Characteristics⁽²⁾

				$T_A = 25^{\circ}C$		
Symbol	Parameter	V _{CC} (V)	C _L (pF)	Тур.	Limit	Units
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	50	0.3	0.5	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	50	-0.3	-0.5	V
V _{IHD}	Minimum HIGH Level Dynamic Input Voltage	3.3	50		2.0	V
V _{ILD}	Maximum LOW Level Dynamic Input Voltage	3.3	50		0.8	V

Note:

2. Input $t_r = t_f = 3ns$

AC Electrical Characteristics

				T	_A = +25°	°C		10°C to 5°C	
Symbol	Parameter	V _{CC} (V)	C _L (pF)	Min.	Тур.	Max.	Min.	Max.	Units
t _{PLH} , t _{PHL}	Propagation Delay,	2.7	15		7.3	15	1.0	18.5	ns
	CP_n to Q_n or \overline{Q}_n		50		9.8	18.5	1.0	22	
		3.3 ± 0.3	15		5.7	9.7	1.0	11.5	
			50		8.2	13.2	1.0	15	
t _{PLH} , t _{PHL}	Propagation Delay,	2.7	15		8.4	15.6	1.0	18.5	ns
	\overline{C}_{Dn} to \overline{S}_{Dn} to Q_n or \overline{Q}_n		50		10.9	19.1	1.0	22	
		3.3 ± 0.3	15		6.6	10.1	1.0	12	
			50		9.1	13.6	1.0	15.5	
t _W	t_W CP_n or \overline{C}_{Dn} or \overline{S}_{Dn} Pulse Width	2.7		8.5			10		ns
		3.3 ± 0.3		6			7		
t _S	Setup Time, D _n to CP _n	2.7		8.0			9.5		ns
		3.3 ± 0.3		5.5			6.5		
t _H	Hold Time, D _n to CP _n	2.7		0.5			0.5		ns
		3.3 ± 0.3		0.5			0.5		
t _{REC}	Recovery Time,	2.7		6.5			7.5		ns
	$\overline{C}P_n$ or \overline{S}_{Dn} to CP_n	3.3 ± 0.3		5.0			5.0		
f _{MAX}	Maximum Clock	2.7	15	55	135		50		MHz
	Frequency		50	45	60		40		
		3.3 ± 0.3	15	95	145		80		
			50	60	85		50		
t _{OSLH} , t _{OSHL}	Output to Output Skew ⁽³⁾	2.7	50			1.5		1.5	ns
		3.3		/		1.5		1.5	

Note:

3. Parameter guaranteed by design $t_{OSLH} = |t_{PLHm} - t_{PLHn}|$, $t_{OSHL} = |t_{PHLm} - t_{PHLn}|$

Capacitance

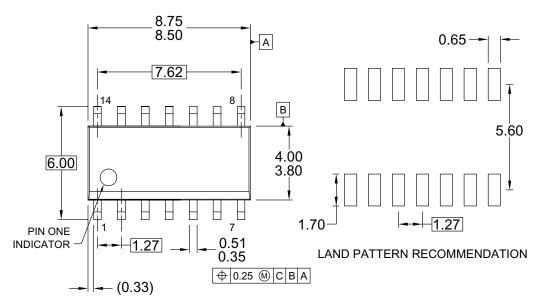
	T _A = +25°C			С	T _A = -4		
Symbol	Parameter	Min.	Тур.	Max.	Min.	Max.	Units
C _{IN}	Input Capacitance		4	10		10	pF
C _{PD}	Power Dissipation Capacitance ⁽⁴⁾		25				pF

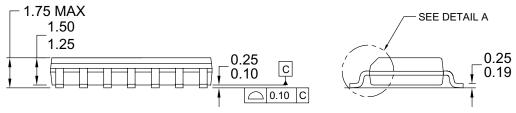
Note

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation: $I_{CC(opr.)} = \frac{C_{PD} \times V_{CC} \times f_{IN} \times I_{CC}}{2 \text{ (per F/F)}}$

Physical Dimensions





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS DO NOT INCLUDE MOLD
 - FLASH OR BURRS.
 - D) LANDPATTERN STANDARD: SOIC127P600X145-14M
 - E) DRAWING CONFORMS TO ASME Y14.5M-1994
 - F) DRAWING FILE NAME: M14AREV13

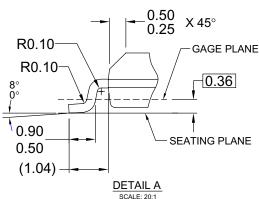
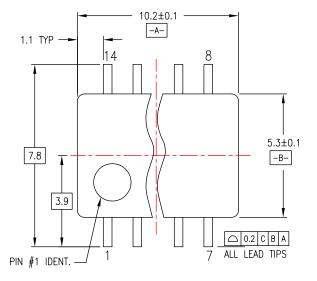


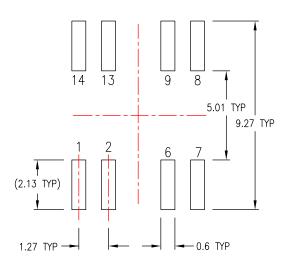
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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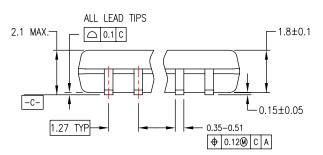
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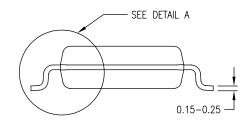
Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATION



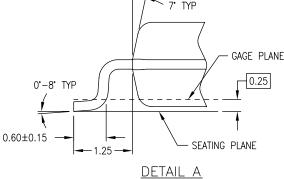


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.

DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued) 5.0±0.1 -A-0.43 TYF 0.65 6.4 4.4±0.1 -B--1.65 3.2 □ 0.2 C B A PIN #1 IDENT. 6 10 0.45-LAND PATTERN RECOMMENDATION SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX □ 0.1 C -0.10 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30⊕ 0.13M ABS CS 12.00°TOP & BOTTOM R0.09 min **GAGE PLANE** 0.25 0°-8° NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153. 0.6±0.1 SEATING PLANE R0.09min VARIATION AB, REF NOTE 6 1 00 **B. DIMENSIONS ARE IN MILLIMETERS DETAIL A**

- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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